

Company Guideline		
R04_0_ General requirements for board and panels		
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	Created / Changed	Approved
by:	Dirk Leder	Grit Stelle
Signature:		

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0. Index of Changes

Index	Date of change	Author	Description of change
00	22.11.2018	N. Schlothauer	Initial version
01	21.08.2019	D. Leder	Mark faulty plates

1. Purpose

This document describes the general design requirements to design and produce a PCB panel for QUNDIS. This is only valid in the latest version. Latest version see 4.2

2. Scope of Application

All PCB Suppliers of the QUNDIS GmbH

3. Requirements

3.1 General Information

The dataset for manufacturer contains:

- gerber data of the PCB
- Mechanical drawing of a PCB and the Panel
- PCB Specification

Please read the *PCB Specification* carefully! You will find there all important parameters for the board.

After creating the Panel, you must send the working gerber data and paste layer to QUNDIS for confirmation.

3.2 Panel design

Use the mechanical drawing from QUNDIS to create the panel design.

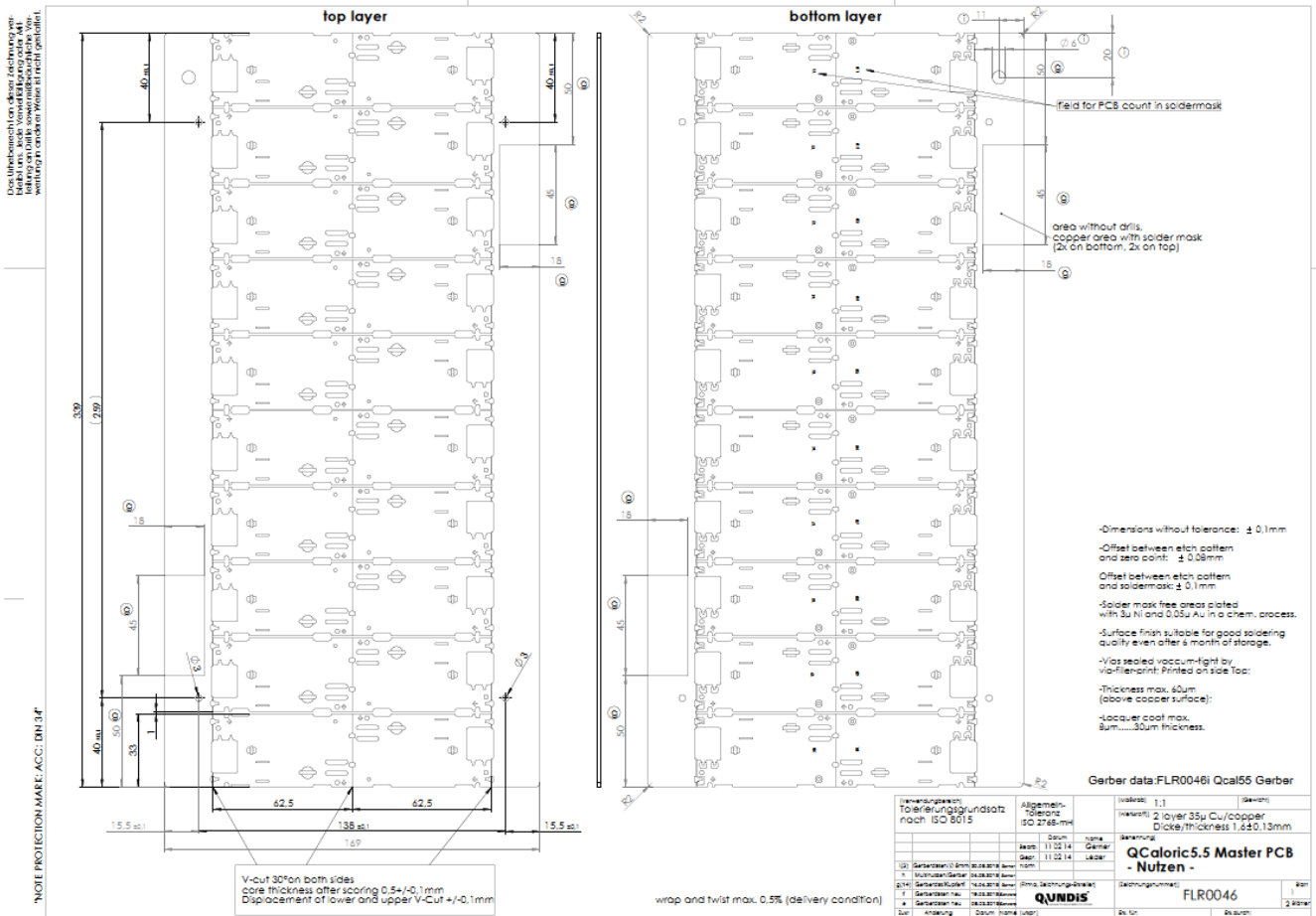
The picture below shows an example of the mechanical drawing for a Panel (e.g. Qcaloric FLR0046i below).

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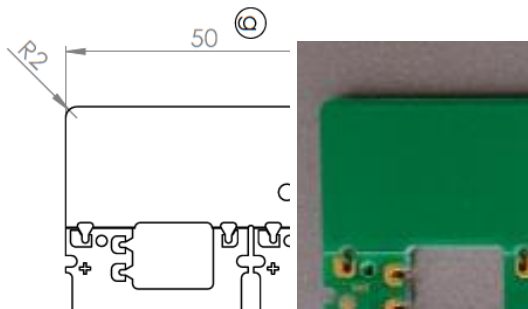
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The following points are necessary for creating each of the Panels.

- 1) Round corners, radius 2mm



- 2) Generally, the area for laser description must be without holes. Full copper and lacquer is also required in this area.



3.3 Solder mask

Read the *PCB Specification* to use the right solder mask material. In general, the solder mask material must be green glossy and laser printable. You must inform QUNDIS, in case of changing the solder mask material. QUNDIS will test some samples and approve the material for the production.

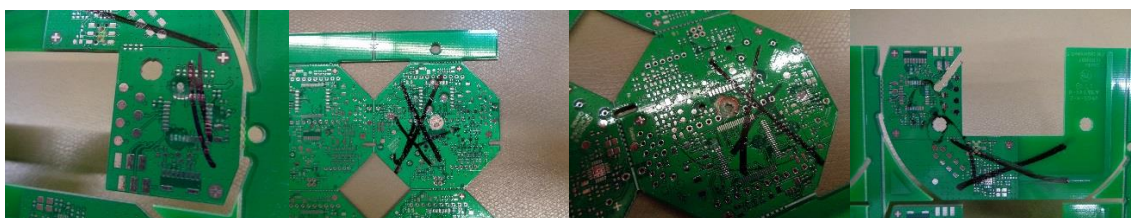
Furthermore, QUNDIS requires a full ROHS and Reach compliant material. The documents for the proof of compliance of the material are required before material release.

3.4 Marking a faulty board in the panel and packaging

You must mark all faulty boards in a panel. No cut-out.

Don't drill or mill the surface of the faulty boards. That causes big trouble in our factory by printing the solder paste.

The pictures below shows some faulty boards with wrong marking.

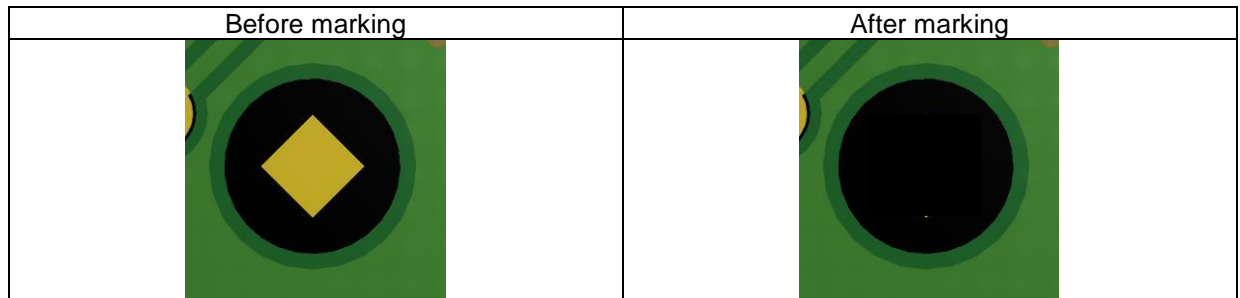


Don't do this in this way!! No drilling or milling!!!

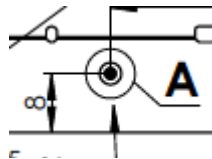
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In case of no skip point on PCB:
 Mark the faulty board by pen with a black "X".

In case of boards with a skip point (see picture below):
 Use the skip point to mark the faulty board. The skip point must be coloured by pen in black.



In case of boards with a mark point in waste area, (see picture below):
 Use the mark point to mark the faulty board. The mark point must be coloured by pen in black.
 Follow the instructions in the drawing!




Please read the *PCB Specification* for the details to marking. E.g. only top side or top and bottom sides to mark.

Use a black waterproof pen to mark the boards.



All faulty boards/ panels must be delivered in separate packing units, protected against humidity (vacuum) and boxes.

All outer packing units must be marked with a coloured sticker if box contains X-out Panels.	
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The vacuum bag with faulty boards / panels must be marked with a red coloured sticker.

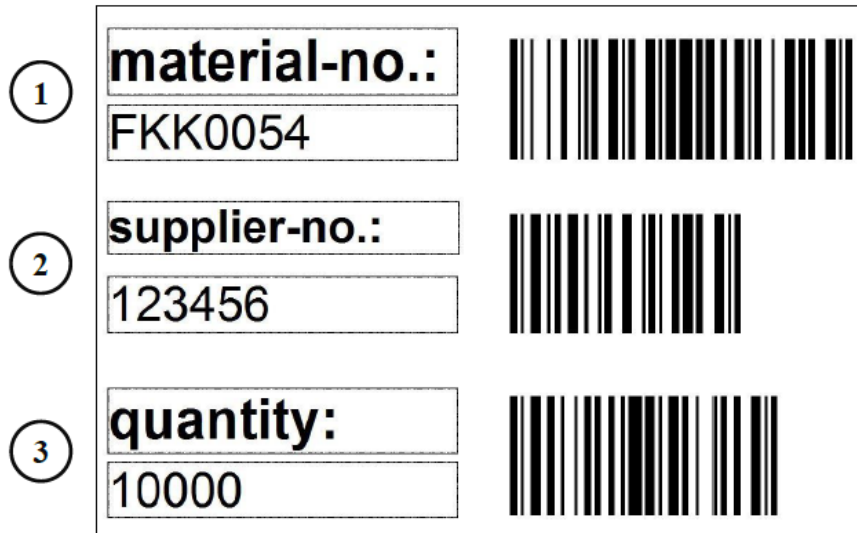


Please pack all the Panels with faulty parts separately!

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3.5 Labelling of outer packages and inner bags

Generally, the label for the outer packages must contain the following information:



- 1 – QUNDIS material number as text and barcode (128)
- 2 – QUNDIS supplier number as text and barcode (128)
- 3 – Package unit quantity as text and barcode (128)

Size of label:

- min. 80 x 50 mm
- clearly readable

Position of label:

- placed in the upper area of the shorter side of each packaging unit
- facing outwards on each pallet for easy recognition
- outer or secondary packaging has to be labelled with the total quantity also




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Generally, the label for inner bags must contain the following information. Variation needs to be confirmed with QUNDIS before the first shipment was sent out.

<u>company</u>		
(P) <u>Cust. Part No:</u>	FLR0012	
Revision:	FLR0012a-V8	
<u>Cust. Part:</u>	<u>Leiterplatte Funkmodul WMZ Fernantenne</u>	
(1T) Lot No:	1589647	
Quantity:	320 (20 panels)	
Faulty circuit boards:	3	
Manuf. Date:	1542	
(12D) <u>Solderable up to:</u>	1642	
Storage conditions:	25°C+/-5K; max. 65% <u>r.h.</u>	
HAL lead-free	<u>Rohs compliant</u>	

Note:

- Size: free
- Quantity: only good PCB's
- Date format (YYWW)
- Data Identifier in barcode as prefix

3.6 Packaging

- No paper between panels
- Vacuum-packed with humidity indicator
- Not more than 20 circuit board panels per packing unit
- Defective panels must be delivered in separate packing units.
- Max. weight per PU: 10 kg

Generally all PCB's must be shrink wrapped in ESD-foil or aluminium foil and must contain a humidity indicator.

An exception to this requirement is the transport from PCB's directly in Europe. Inner-European transport can be done in needled shrink wrap foil without humidity indicator.

3.7 Certificates / Documentary Proof

- electrical test
- In-process inspection / outgoing inspection
- documentation of tests, these must be made available within 3 working days on request

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3.8 Delivery Quality

Delivery Quality must be according to our PCB dataset, Ordering Terms and Conditions and information according to our Purchase Order.

Furthermore we accept max. 5% of panels in order quantity with defect units.

On Panels we accept the following defect PCB's:

circuit boards/ panel	max. count of defective circuit boards/ panel
1 to2	0
3 to 10	2
>11	3

3.9 Limit Values

- Storage temperature range: -40°C to 60°C at a relative humidity of less than 60 %
- Operating temperature range: -40°C to 90°C
- Minimum processability: HAL- 6 month; NiAu - 1 year

3.10 Changes

In the event of new boards and new boards revision, QUNDIS will check and confirm the working gerber data.

COC is required with the first shipment from mass production factory.

PCN is required for any change in mass production process at production factory.

4. General information

4.1 Uncertainty

In the event of any uncertainty in requirements, please contact QUNDIS urgently.

4.2 Business Data

- QUNDIS General Packaging and Delivery Guidelines
(<http://QUNDIS.com/service/supplier/transport-recycling-guidelines-2/>)
- QUNDIS R17_0_Handling of substances and goods (Prohibitions on substances)
(<http://QUNDIS.com/service/supplier/gtc>)
- QUNDIS general delivery specification – latest version
(<http://QUNDIS.com/service/supplier/gtc>)

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5. Confirmation by Engineering

Name: D. Leder

Date: 22.08.2019

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(Signature)

6. Confirmation by Purchasing

Name: Nicole Schlothauer

Date: 22.08.2019

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(Signature)

7. Confirmation by Quality Department

Name: G. Stelle

Date: 22.08.2019

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(Signature)